

PTC thermistors for overcurrent protection

SMDs, EIA sizes 3225 and 4032, 24 V

 Series/Type:
 B59101, B59201, B59301

 Date:
 January 2016

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Applications

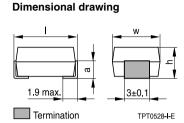
- Overcurrent protection
- Short circuit protection

Features

- Molded epoxy encapsulation, lead-free tinned solder terminals
- Marking: Type, manufacturer's logo, reference temperature in °C
- Suitable for wave and reflow soldering
- Suitable for automatic placement
- Qualification based on AEC-Q200, Rev. D
- Moisture sensitivity level (MSL) 1 acc. to JEDEC J-STD-020D
- RoHS-compatible

Delivery mode

Blister tape, 330-mm reel with 16-mm tape, taping to IEC 60286-3

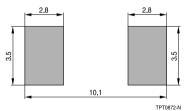


Dimensions (mm)

Туре	h ±0.5	w ±0.5	l ±0.5	a ±0.3	Size
Reference temperature T _{ref} = 80 °C					
P1101	3.3	6.3	8.0	1.7	3225
P1201	3.3	6.3	8.0	1.7	3225
P1301	3.3	8.0	10.0	2.3	4032
Reference temperature T _{ref} = 120 °C					
P1101	3.3	6.3	8.0	1.7	3225
P1201	3.3	6.3	8.0	1.7	3225
P1301	3.3	8.0	10.0	2.3	4032

Geometry of solder pads

EIA case size 3225

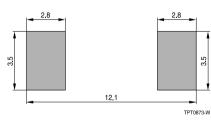


Recommended maximum dimensions (mm)

General technical data

Max. operating voltage	(T _A = 60 °C)	V _{max}	30	V DC or V AC
Rated voltage		V _R	24	V DC or V AC
Switching cycles		Ν	100	
Tolerance of R _R		ΔR_{R}	±25	%
Operating temperature range	(V = 0)	T _{op}	-40/+125	°C
Operating temperature range	$(V = V_{max})$	T _{op}	-40/+60	°C

EIA case size 4032





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Electrical specifications and ordering codes

Туре	I _R	I _s	I _{Smax}	l _r	R _R	R _{min}	Ordering code
			$(V = V_{max})$	(typ.)			
				$(V = V_{max})$			
	mA	mA	Α	mA	Ω	Ω	
Reference	ce tempera	ture $T_{ref} = 8$	30 °C				
P1301	205	420	1.6	38	3.1	1.85	B59301P1080A062
P1201	165	340	1.0	34	4.6	2.70	B59201P1080A062
P1101	90	185	0.7	25	13	7.80	B59101P1080A062
Reference temperature T _{ref} = 120 °C							
P1301	310	640	1.6	53	3.1	1.85	B59301P1120A062
P1201	265	545	1.0	45	4.6	2.70	B59201P1120A062
P1101	170	355	0.7	35	13	7.80	B59101P1120A062

Reliability data

Test	Standard	Test conditions	$ \Delta R_{25}/R_{25} $
Electrical endurance,	IEC 60738-1	Room temperature, I _{Smax} ; V _{max}	< 25%
cycling		Number of cycles: 100	
Electrical endurance,	IEC 60738-1	Storage at V_{max} and $T_{op,max}$ (@ V_{max})	< 25%
constant		Test duration: 1000 h	
Damp heat	IEC 60738-1	Temperature of air: 40 °C	< 10%
		Relative humidity of air: 93%	
		Duration: 56 days	
		Test according to IEC 60068-2-78	
Rapid change	IEC 60738-1	$T_1 = T_{op,min} (0 V), T_2 = T_{op,max} (0 V)$	< 10%
of temperature		Number of cycles: 5	
		Test duration: 30 min	
		Test according to IEC 60068-2-14, test Na	
Shock	IEC 60738-1	Acceleration: 400 m/s ²	< 5%
		Pulse duration: 6 ms; 6×5000 pulses	
Bending test	IEC 60738-1	Components reflow-soldered to test board	< 10%
		Maximum bending: 2 mm	
		Test according to IEC 60068-2-21, test Ue	



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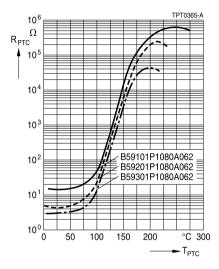
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Characteristics (typical) for T_{ref} = 80 °C

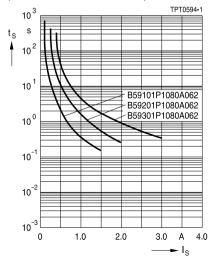
PTC resistance R_{PTC} versus

PTC temperature T_{PTC}

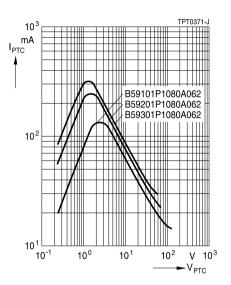
(measured at low signal voltage)



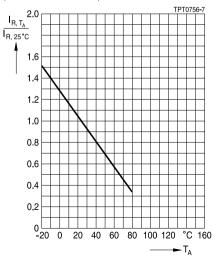
Switching time t_s versus switching current I_s (measured at 25 °C in still air)



PTC current I_{PTC} versus PTC voltage V_{PTC} (measured at 25 °C in still air)



Rated current I_{R} versus ambient temperature T_{A} (measured in still air)



Please



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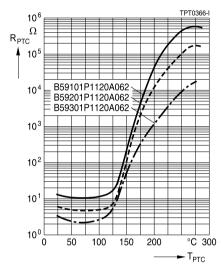
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Characteristics (typical) for T_{ref} = 120 °C

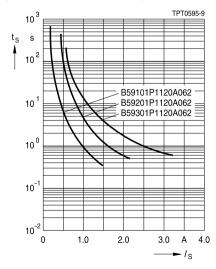
PTC resistance R_{PTC} versus

PTC temperature T_{PTC}

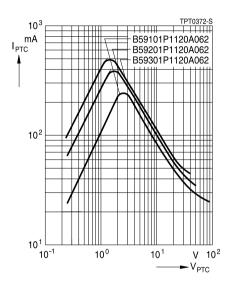
(measured at low signal voltage)



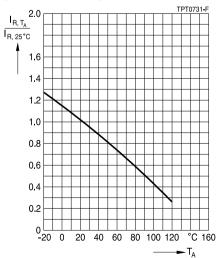
Switching time t_s versus switching current I_s (measured at 25 °C in still air)



PTC current I_{PTC} versus PTC voltage V_{PTC} (measured at 25 °C in still air)



Rated current I_R versus ambient temperature T_A (measured in still air)





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Cautions and warnings

General

- EPCOS thermistors are designed for specific applications and should not be used for purposes not identified in our specifications, application notes and data books unless otherwise agreed with EPCOS during the design-in-phase.
- Ensure suitability of thermistor through reliability testing during the design-in phase. The thermistors should be evaluated taking into consideration worst-case conditions.

Storage

- Store thermistors only in original packaging. Do not open the package prior to processing.
- Storage conditions in original packaging: storage temperature -25 °C ... +45 °C, relative humidity ≤75% annual mean, maximum 95%, dew precipitation is inadmissible.
- Avoid contamination of thermistors surface during storage, handling and processing.
- Avoid storage of thermistor in harmful environment with effect on function on long-term operation (examples given under operation precautions).
- Use thermistor within the following period after delivery:
 - Through-hole devices (housed and leaded PTCs): 24 months
 - Motor protection sensors, glass-encapsulated sensors and probe assemblies: 24 months
 - Telecom pair and quattro protectors (TPP, TQP): 24 months
 - Leadless PTC thermistors for pressure contacting: 12 months
 - Leadless PTC thermistors for soldering: 6 months
 - SMDs in EIA sizes 3225 and 4032, and for PTCs with metal tags: 24 months
 - SMDs in EIA sizes 1210 and smaller: 12 months

Handling

- PTCs must not be dropped. Chip-offs must not be caused during handling of PTCs.
- The ceramic and metallization of the components must not be touched with bare hands. Gloves are recommended.
- Avoid contamination of thermistor surface during handling.

Soldering (where applicable)

- Use rosin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.
- Standard PTC heaters are not suitable for soldering.



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Mounting

- Electrode must not be scratched before/during/after the mounting process.
- Contacts and housing used for assembly with thermistor have to be clean before mounting. Especially grease or oil must be removed.
- When PTC thermistors are encapsulated with sealing material, the precautions given in chapter "Mounting instructions", "Sealing and potting" must be observed.
- When the thermistor is mounted, there must not be any foreign body between the electrode of the thermistor and the clamping contact.
- The minimum force and pressure of the clamping contacts pressing against the PTC must be 10 N and 50 kPa, respectively. In case the assembly is exposed to mechanical shock and/ or vibration this force should be higher in order to avoid movement of the PTC during operation.
- During operation, the thermistor's surface temperature can be very high. Ensure that adjacent components are placed at a sufficient distance from the thermistor to allow for proper cooling at the thermistors.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of thermistor. Be sure that surrounding parts and materials can withstand this temperature.
- Avoid contamination of thermistor surface during processing.

Operation

- Use thermistors only within the specified temperature operating range.
- Use thermistors only within the specified voltage and current ranges.
- Environmental conditions must not harm the thermistors. Use thermistors only in normal atmospheric conditions. Avoid use in deoxidizing gases (chlorine gas, hydrogen sulfide gas, ammonia gas, sulfuric acid gas etc), corrosive agents, humid or salty conditions. Contact with any liquids and solvents should be prevented.
- Be sure to provide an appropriate fail-safe function to prevent secondary product damage caused by abnormal function (e.g. use VDR for limitation of overvoltage condition).

This listing does not claim to be complete, but merely reflects the experience of EPCOS AG.

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Symbols and terms

Symbol	Term
A	Area
С	Capacitance
C _{th}	Heat capacity
f	Frequency
I	Current
I _{max}	Maximum current
I _R	Rated current
I _{res}	Residual current
I _{PTC}	PTC current
l _r	Residual currrent
l _{r,oil}	Residual currrent in oil (for level sensors)
I _{r,air}	Residual currrent in air (for level sensors)
I _{RMS}	Root-mean-square value of current
l _s	Switching current
I _{Smax}	Maximum switching current
LCT	Lower category temperature
Ν	Number (integer)
N _c	Operating cycles at V _{max} , charging of capacitor
N _f	Switching cycles at V _{max} , failure mode
Р	Power
P ₂₅	Maximum power at 25 °C
P _{el}	Electrical power
P _{diss}	Dissipation power
R _G	Generator internal resistance
R _{min}	Minimum resistance
R _R	Rated resistance @ rated temperature T _R
ΔR_R	Tolerance of R _R
R _P	Parallel resistance
R _{PTC}	PTC resistance
R _{ref}	Reference resistance
R _s	Series resistance
R ₂₅	Resistance at 25 °C
R _{25,match}	Resistance matching per reel/ packing unit at 25 °C
ΔR_{25}	Tolerance of R ₂₅



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Т	Temperature
t	Time
T _A	Ambient temperature
t _a	Thermal threshold time
T _c	Ferroelectric Curie temperature
t _E	Settling time (for level sensors)
T _R	Rated temperature @ 25 °C or otherwise specified in the data sheet
T _{sense}	Sensing temperature
T _{op}	Operating temperature
T _{PTC}	PTC temperature
t _R	Response time
T _{ref}	Reference temperature
T _{Rmin}	Temperature at minimum resistance
t _s	Switching time
T _{surf}	Surface temperature
UCT	Upper category temperature
V or V_{el}	Voltage (with subscript only for distinction from volume)
V _{c(max)}	Maximum DC charge voltage of the surge generator
$V_{F,max}$	Maximum voltage applied at fault conditions in protection mode
V _{RMS}	Root-mean-square value of voltage
V_{BD}	Breakdown voltage
V _{ins}	Insulation test voltage
$V_{\text{link,max}}$	Maximum link voltage
V _{max}	Maximum operating voltage
$V_{max,dyn}$	Maximum dynamic (short-time) operating voltage
V _{meas}	Measuring voltage
V _{meas,max}	Maximum measuring voltage
V _R	Rated voltage
V _{PTC}	Voltage drop across a PTC thermistor
α	Temperature coefficient
Δ	Tolerance, change
δ_{th}	Dissipation factor
$ au_{th}$	Thermal cooling time constant
λ	Failure rate
e	Lead spacing (in mm)



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